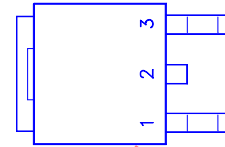
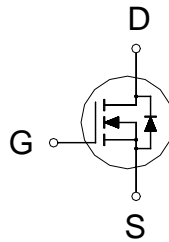


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
25	4m	75A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25\text{ }^\circ\text{C}$	I_D	75	A
	$T_C = 100\text{ }^\circ\text{C}$		50	
Pulsed Drain Current ¹		I_{DM}	200	
Avalanche Current		I_{AS}	45	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	100	mJ
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	96	W
	$T_C = 100\text{ }^\circ\text{C}$		32.75	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^\circ\text{C}$
Lead Temperature (¹ / ₁₆ " from case for 10 sec.)		T_L	275	

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.3	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		75	

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

ELECTRICAL CHARACTERISTICS ($T_C = 25\text{ }^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	25			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	1.5	3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}, T_J = 125\text{ }^\circ\text{C}$			25	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10\text{V}, I_D = 45\text{A}$		3.5	4.0	m
		$V_{GS} = 4.5\text{V}, I_D = 30\text{A}$		4.8	6.0	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 15\text{V}, I_D = 30\text{A}$		56		S

DYNAMIC					
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		4018	pF
Output Capacitance	C_{oss}			1560	
Reverse Transfer Capacitance	C_{rss}			420	
Total Gate Charge ²	Q_g	$V_{DS} = 10V, V_{GS} = 10V,$ $I_D = 40A$		42	nC
Gate-Source Charge ²	Q_{gs}			15	
Gate-Drain Charge ²	Q_{gd}			22.5	
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 15V,$ $I_D \cong 30A, V_{GS} = 10V, R_{GS} = 2.7$		16.5	nS
Rise Time ²	t_r			19	
Turn-Off Delay Time ²	$t_{d(off)}$			48	
Fall Time ²	t_f			28	
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25^\circ C$)					
Continuous Current	I_S			75	A
Pulsed Current ³	I_{SM}			200	A
Forward Voltage ¹	V_{SD}	$I_F = 45A, V_{GS} = 0V$		1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 45A, di_F/dt = 100A / \mu S$		30	nS
Peak Reverse Recovery Current	$I_{RM(REC)}$			200	A
Reverse Recovery Charge	Q_{rr}			14	nC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

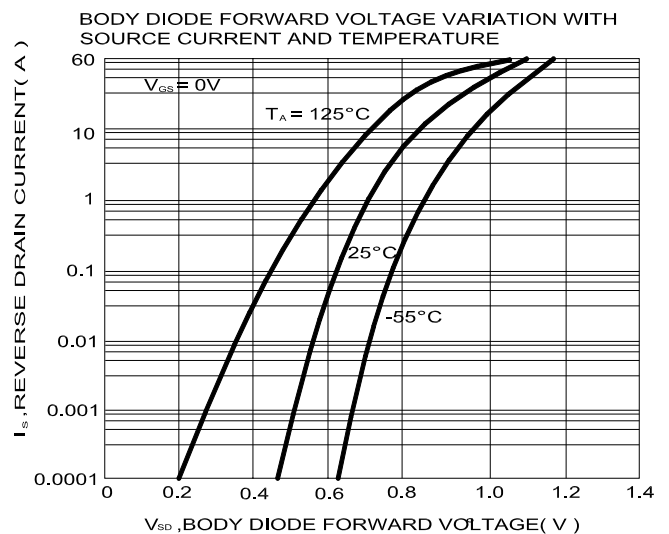
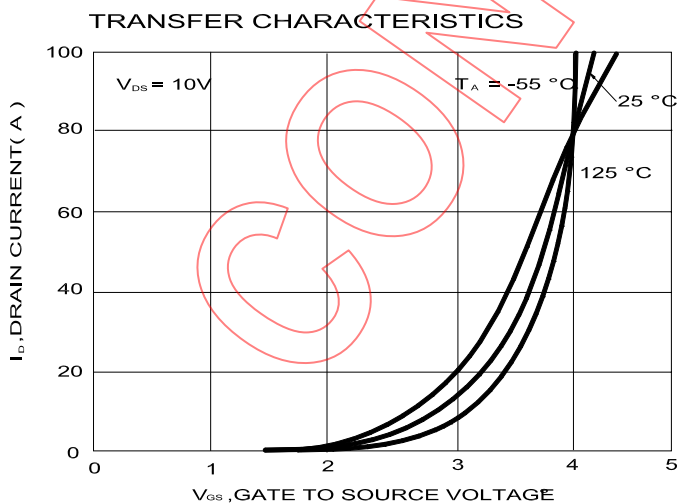
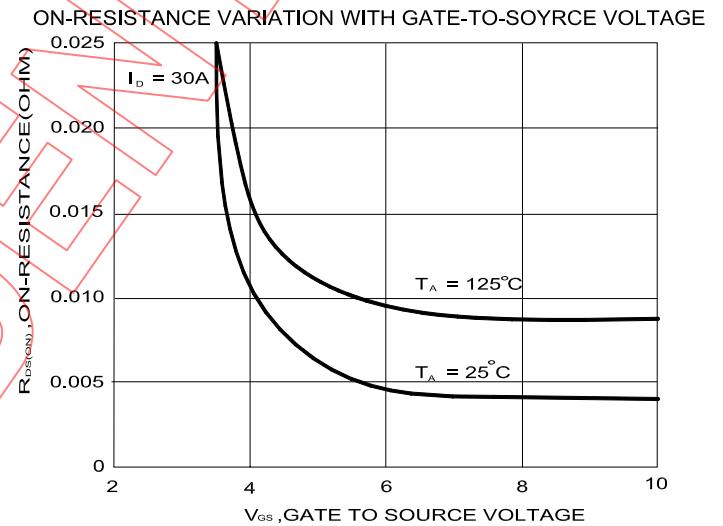
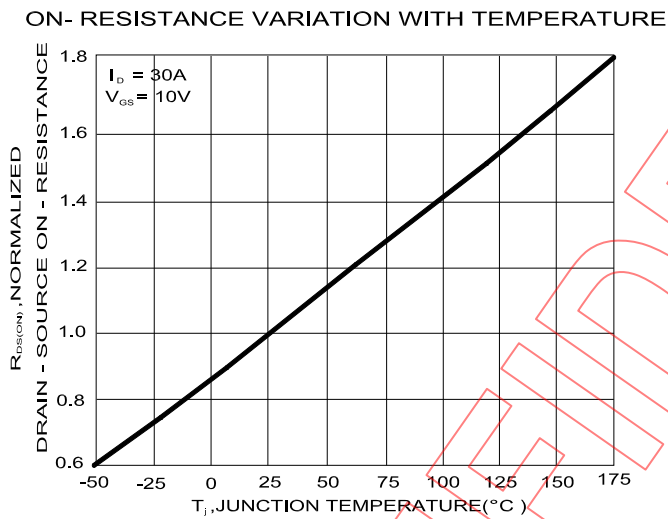
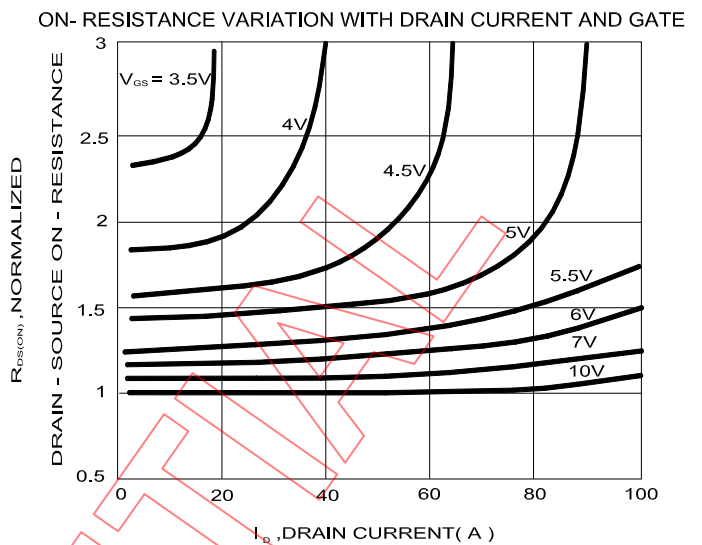
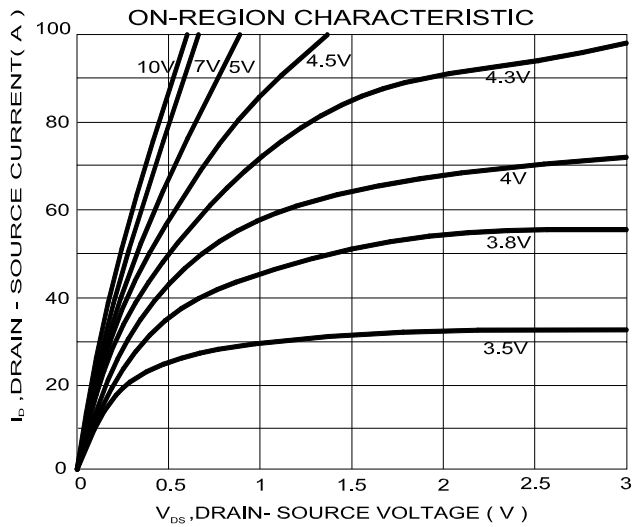
²Independent of operating temperature.

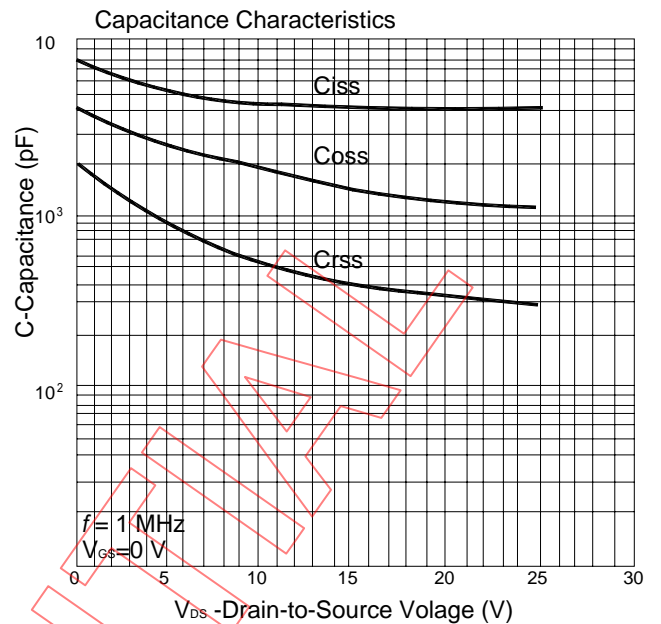
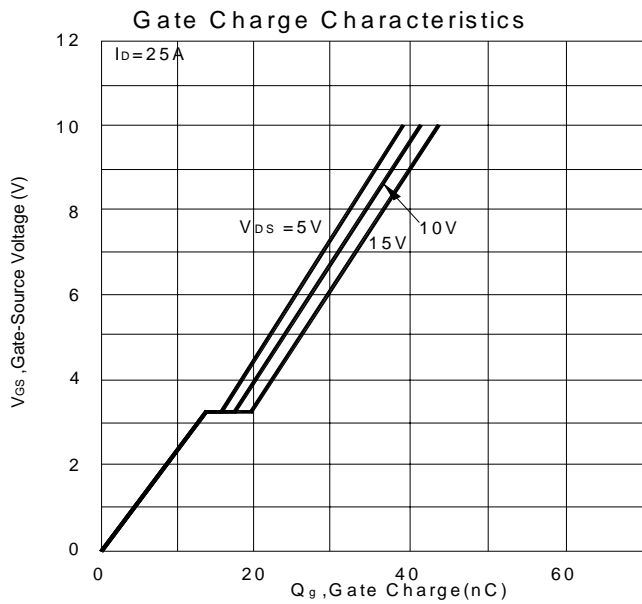
³Pulse width limited by maximum junction temperature.

REMARK: THE PRODUCT MARKED WITH "P0403BDG", DATE CODE or LOT #

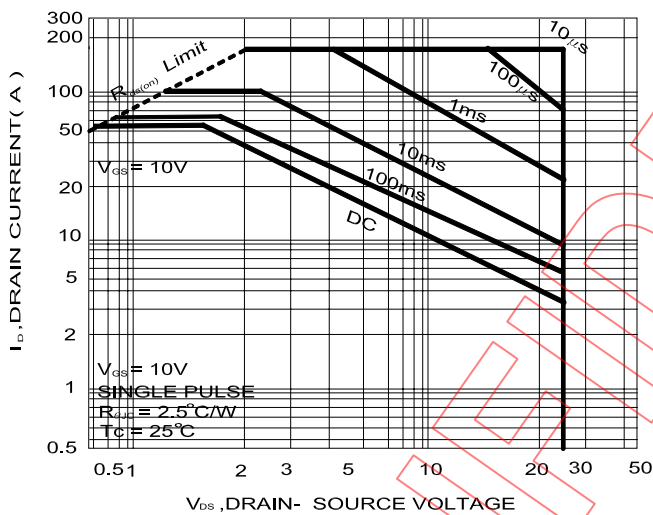
Orders for parts with Lead-Free plating can be placed using the PXXXXXXG parts name.



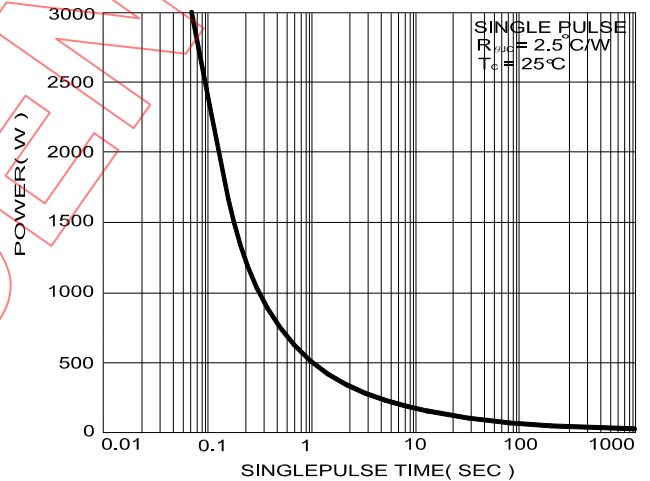




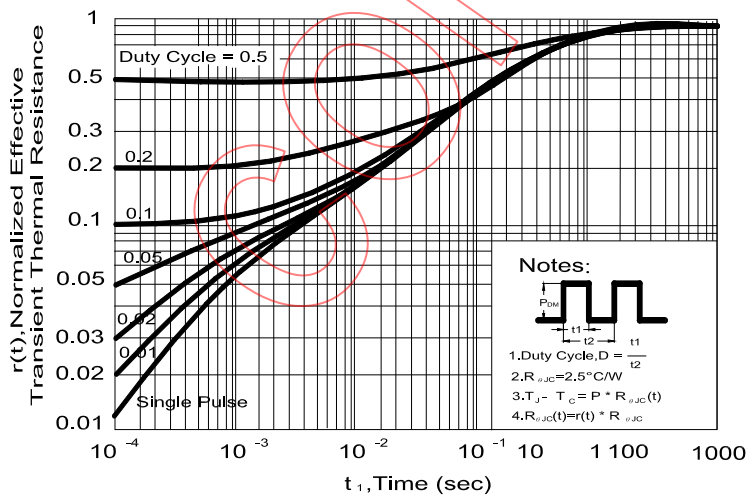
MAXIMUM SAFE OPERATING AREA



SINGLE PULSE MAXIMUM POWER DISSIPATION



Transient Thermal Response Curve



TO-252 (DPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	9.35		10.4	H	0.89		2.03
B	2.2		2.4	I	6.4		6.6
C	0.45		0.6	J	5.2		5.5
D	0.89		1.5	K	0.6		1
E	0.45		0.69	L	0.5		0.9
F	0.03		0.23	M	4.4		4.6
G	5.2		6.2	N			

